

Frore Systems unleashes increased performance for Edge AI with AirJet®PAK, an ultra-thin, plug and play, active heat removal solution.

SAN JOSE, California – May 29, 2024 – On the heels of their \$80M Series C fundraising led by Fidelity Management & Research Company, Frore Systems, a member of the NVIDIA Inception Program, today announced three new plug and play, active heat removal modules designed to meet the rapidly growing demand for Edge AI. The AirJet®PAKs, only 6mm thick, complement the NVIDIA Jetson Orin system-on-modules, and are available in three sizes: AirJet®PAK 5C-25 removes up to 25 watts of heat and supports up to 100 TOPS, AirJet®PAK 3C-15 removes up to 15 watts of heat and supports up to 70 TOPS, and AirJet®PAK 2C-10 removes up to 10 watts of heat and supports up to 50 TOPS.

The AirJet PAK integrates multiple AirJet, the world's first solid-state active cooling chip, to remove the increasing heat generated by intense AI workloads. Removing this heat unleashes the AI performance needed for Edge AI in key markets including autonomous vehicles, robotics, industrial automation, smart cities, healthcare, and retail analytics.

AirJet PAKs are a fully integrated, self-contained, plug and play active cooling solution that are a mere 6mm thick and can be easily added to a host device to enable the performance needed to perform AI workloads at the Edge in smaller, silent, lighter, vibration free, and dustproof, compact devices. The need for improved cooling to enable AI is increasing rapidly, and with a forecast of demand for Edge AI Computing estimated to increase by over 300% by 2030, it will not slow down anytime soon.

Heat, which limits performance, is now the single biggest problem facing the computing industry. AirJet PAKs' ability to dissipate heat, unleashing performance, is essential for AI applications.

SmartCow, a leading AI engineering company, and an NVIDIA Preferred Partner, plans to be an early adopter of AirJet PAK. "We are currently integrating AirJet PAK into a new product line called 'Uranus + with AirJet' - a cutting-edge, faster, smaller, lighter, silent and dustproof AI edge embedded system." said Ravi Kiran, CEO of SmartCow. "We are excited to combine AirJet's innovative technology with our advanced systems to deliver a truly differentiated product that better enables Smart Cities, Smart Retail, and AI Gateway Entrances."

The ultra-thin plug and play AirJet PAK active heat removal modules are:

- **AirJet®PAK 5C-25:** Complementing the NVIDIA Jetson Orin NX 16GB, the AirJet PAK 5C-25 contains 5 AirJet chips, measures 164x63x6mm, removes up to 25 watts of heat, and supports up to 100 TOPS.
- **AirJet®PAK 3C-15:** Complementing the NVIDIA Jetson Orin Nano 8GB, the AirJet PAK 3C-15 contains 3 AirJet chips, measures 106x63x6mm, removes up to 15 watts of heat, and supports up to 70 TOPS.
- **AirJet®PAK 2C-10:** Complementing the NVIDIA Jetson Orin Nano 4GB, the AirJet PAK 2C-10 contains 2 AirJet chips, measures 106x63x6mm, removes up to 10 watts of heat, and supports up to 50 TOPS.

AirJet PAKs:

- Are fully self-contained, plug and play thermal solutions that include multiple AirJet chips and the drive circuitry

- Mount directly on NVIDIA's Jetson Orin Nano/NX Modules
- Operate autonomously
- Are ultra-thin, silent, vibration free and dustproof
- Support up to 100 TOPS
- Dissipate up to 25 Watts of Heat

The AirJet PAKs make increasing performance a breeze, enhancing AI processing capabilities in faster, silent, thinner, lighter, vibration free and dustproof devices.

"Cooling is critical to enable the performance needed to achieve the AI vision – today and in the future. Traditional bulky and noisy thermal solutions, like fans, simply don't meet the challenge." said Dr. Seshu Madhavapeddy, founder and CEO of Frore Systems. "We are thrilled to announce the AirJet PAK, an ultra-thin plug and play solution that is scalable and enables Edge AI platform manufacturers to unleash AI performance in compact form factors. The AirJet PAK is an easily integrated thermal solution that makes devices faster, silent, thinner, lighter, vibration free and dustproof. It is the ideal thermal solution for products needing the latest AI capabilities."

The new AirJet PAK, and an impressive array of additional AirJet demonstrations showing increased performance in a wide range of applications, will be on display next week, June 4 – 7, at COMPUTEX Taipei 2024 - one of the largest computer and technology trade shows in the world.

About Frore Systems:

Frore Systems is the developer of breakthrough thermal technology for electronic and consumer devices. The company's active cooling solutions, the AirJet® Mini, AirJet Mini Slim and the new AirJet PAKs, are integrated into devices to remove heat silently, resulting in major performance gains and enabling thinner, lighter, silent, vibration free and dustproof devices. Frore Systems is headquartered in San Jose, CA with an office and manufacturing facility in Taiwan. For more information, please visit <https://froresystems.com/>

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